

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

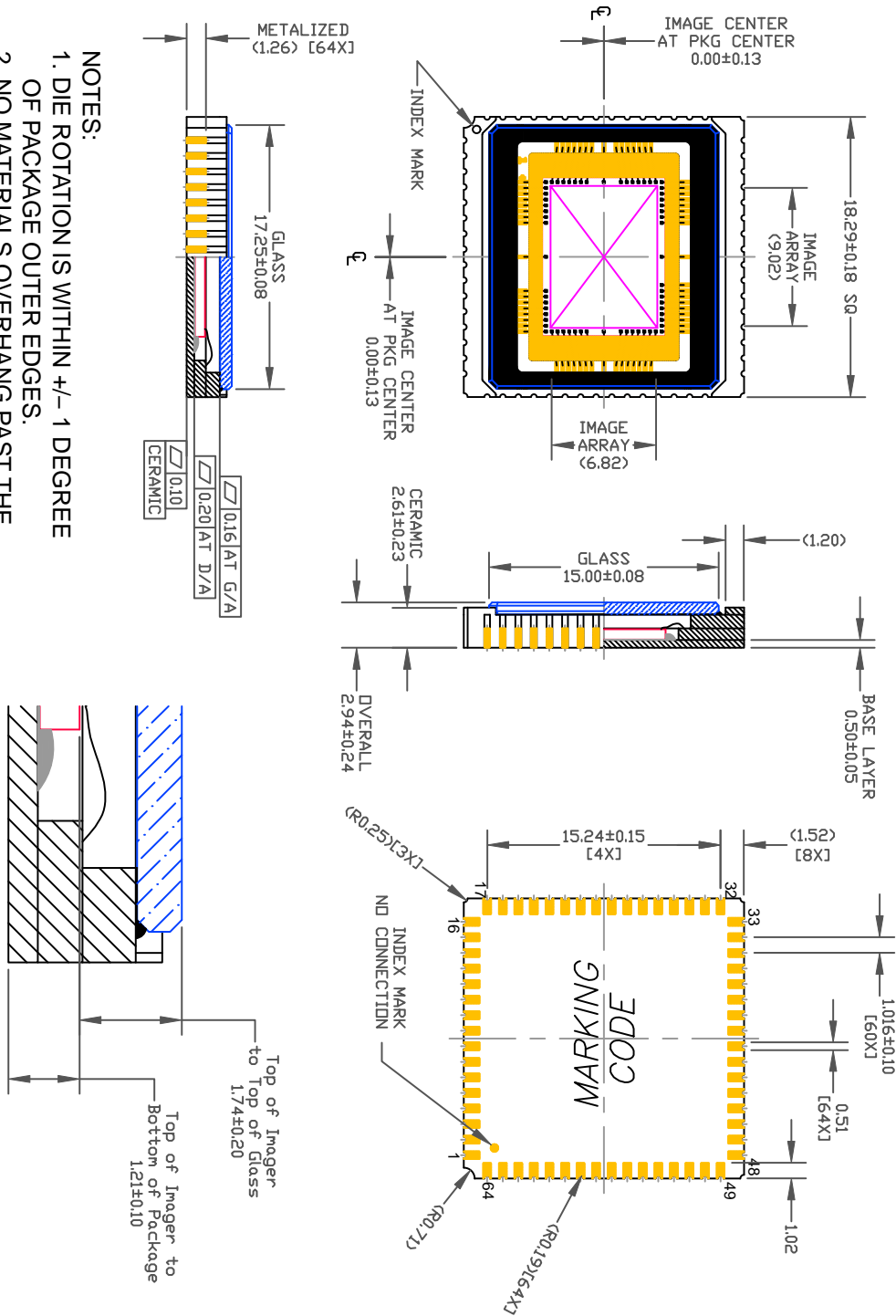
ON Semiconductor®



CLCC64 18.29x18.29  
CASE 848AD  
ISSUE A

DATE 30 JUL 2014

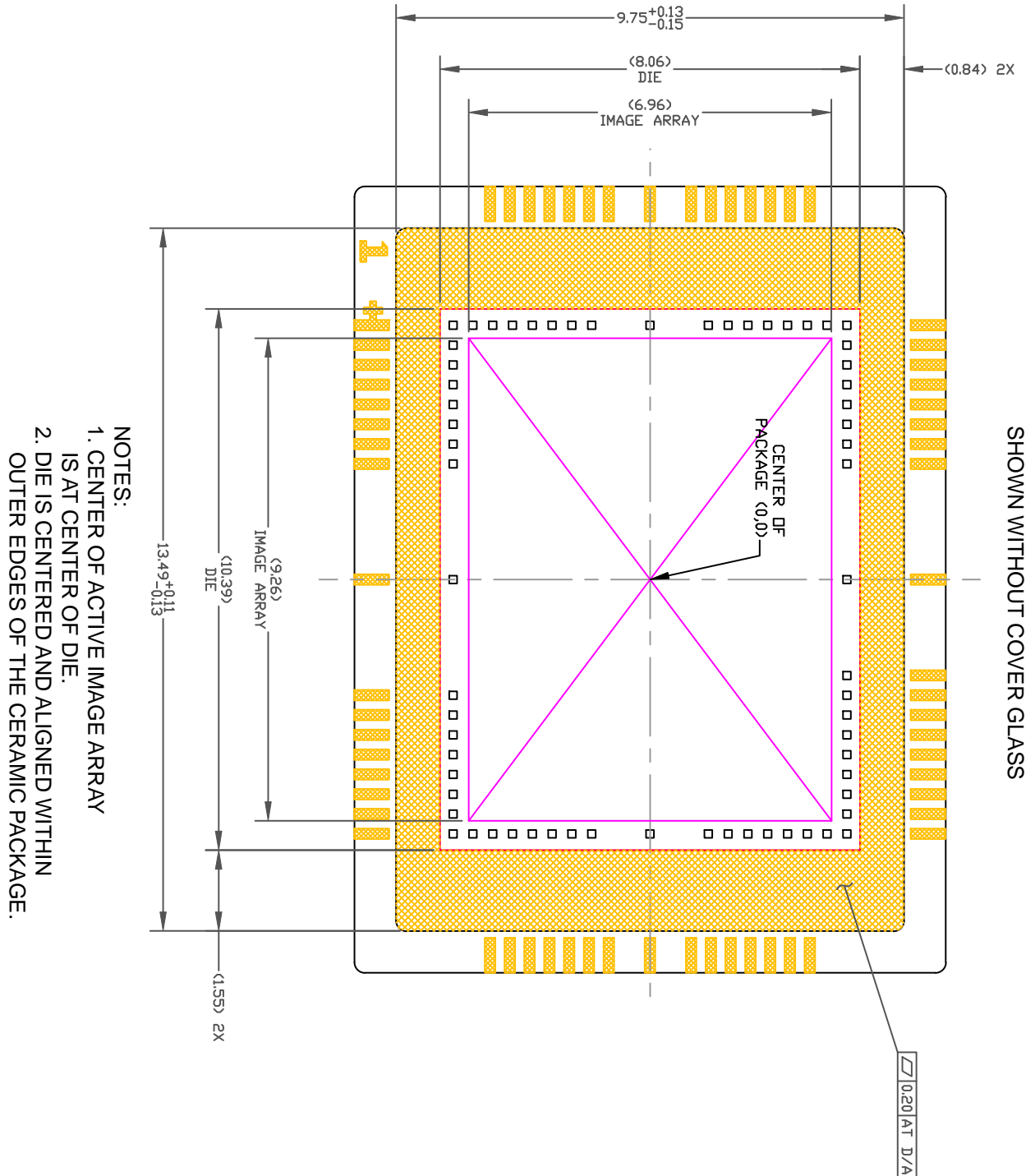
- NOTES:
1. DIE ROTATION IS WITHIN +/- 1 DEGREE OF PACKAGE OUTER EDGES.
  2. NO MATERIALS OVERHANG PAST THE OUTER EDGES OF THE CERAMIC PACKAGE.



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- NOTES:
1. CENTER OF ACTIVE IMAGE ARRAY IS AT CENTER OF DIE.
  2. DIE IS CENTERED AND ALIGNED WITHIN OUTER EDGES OF THE CERAMIC PACKAGE.

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